

HIGH RELIABILITY MULTILAYER CIRCUIT
SUBSTRATES AND METHODS FOR THEIR
FORMATION

Inventors: Rajiv Shah et al.

Attorney: Ted R. Rittmaster - 047711-0319

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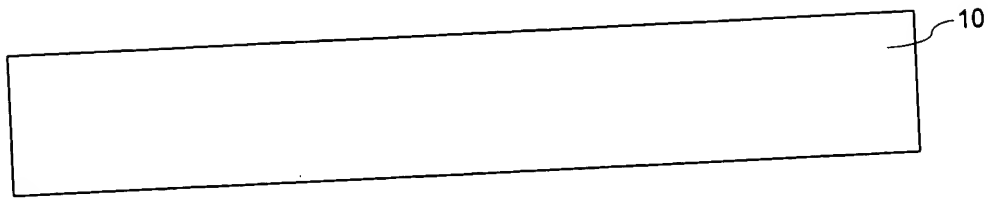


Figure 1a

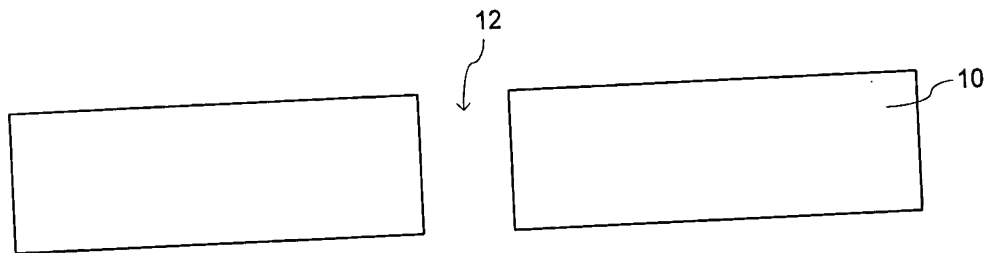


Figure 1b

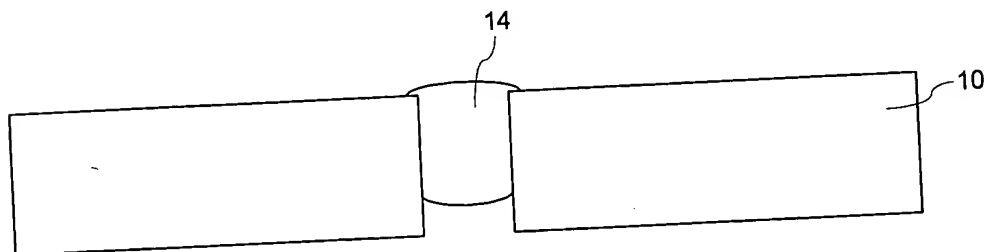


Figure 1c

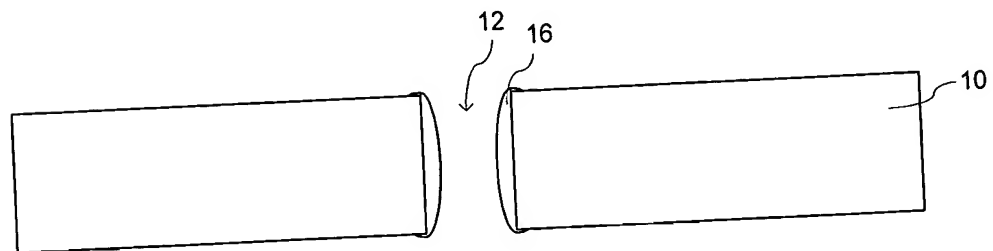


Figure 1d

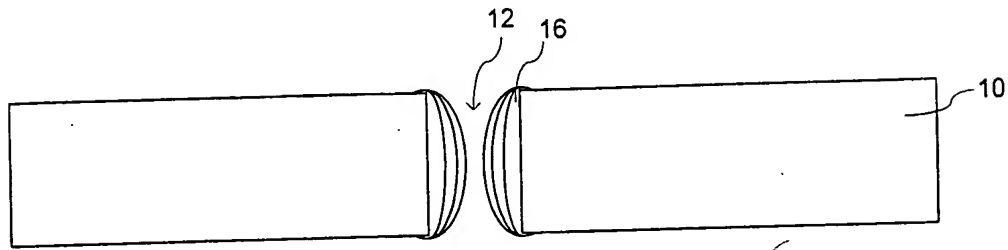


Figure 1e

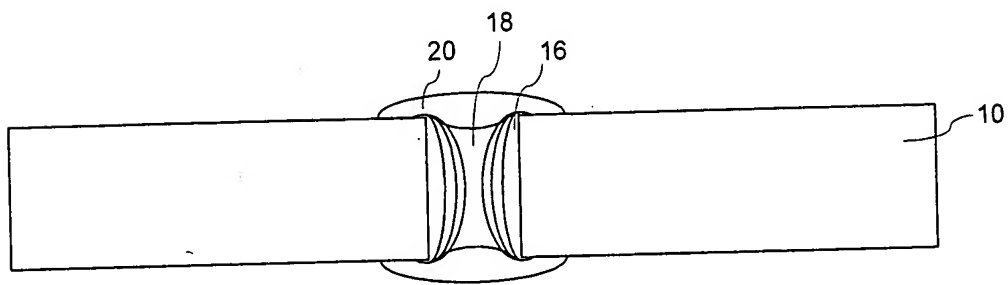


Figure 1f

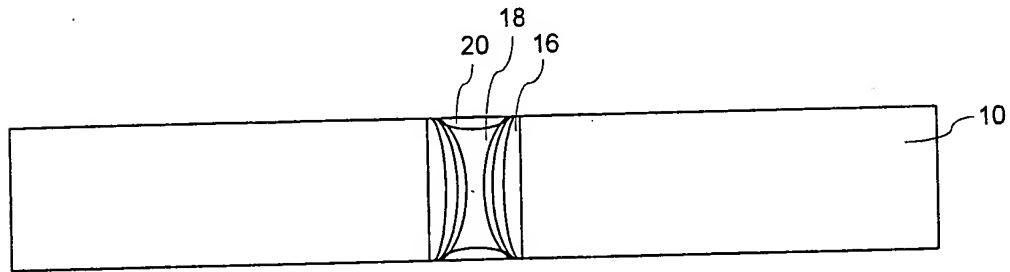


Figure 1g

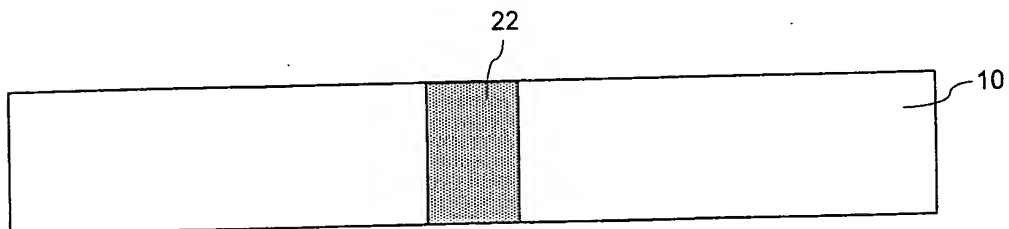


Figure 1h

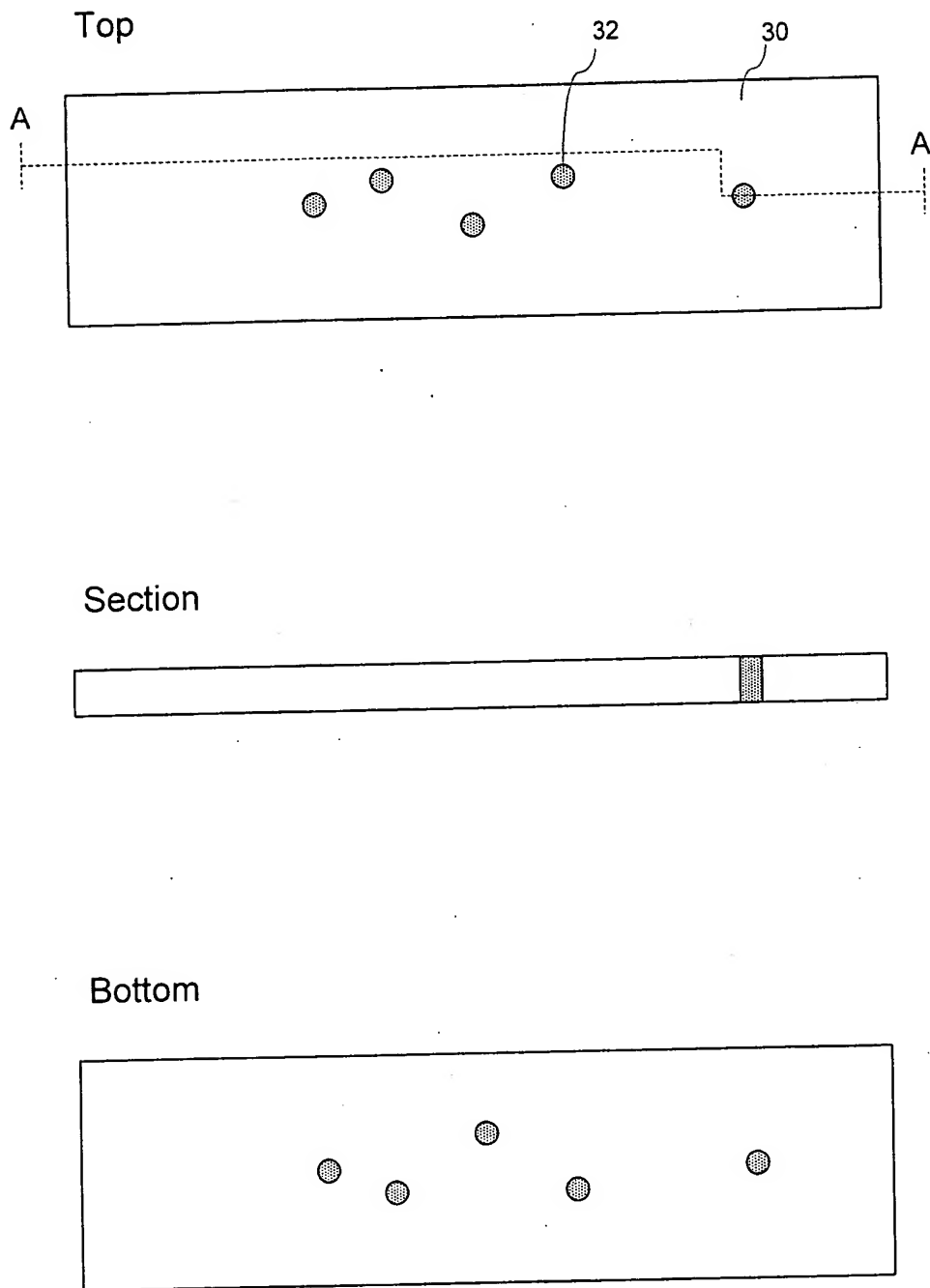


Figure 2a

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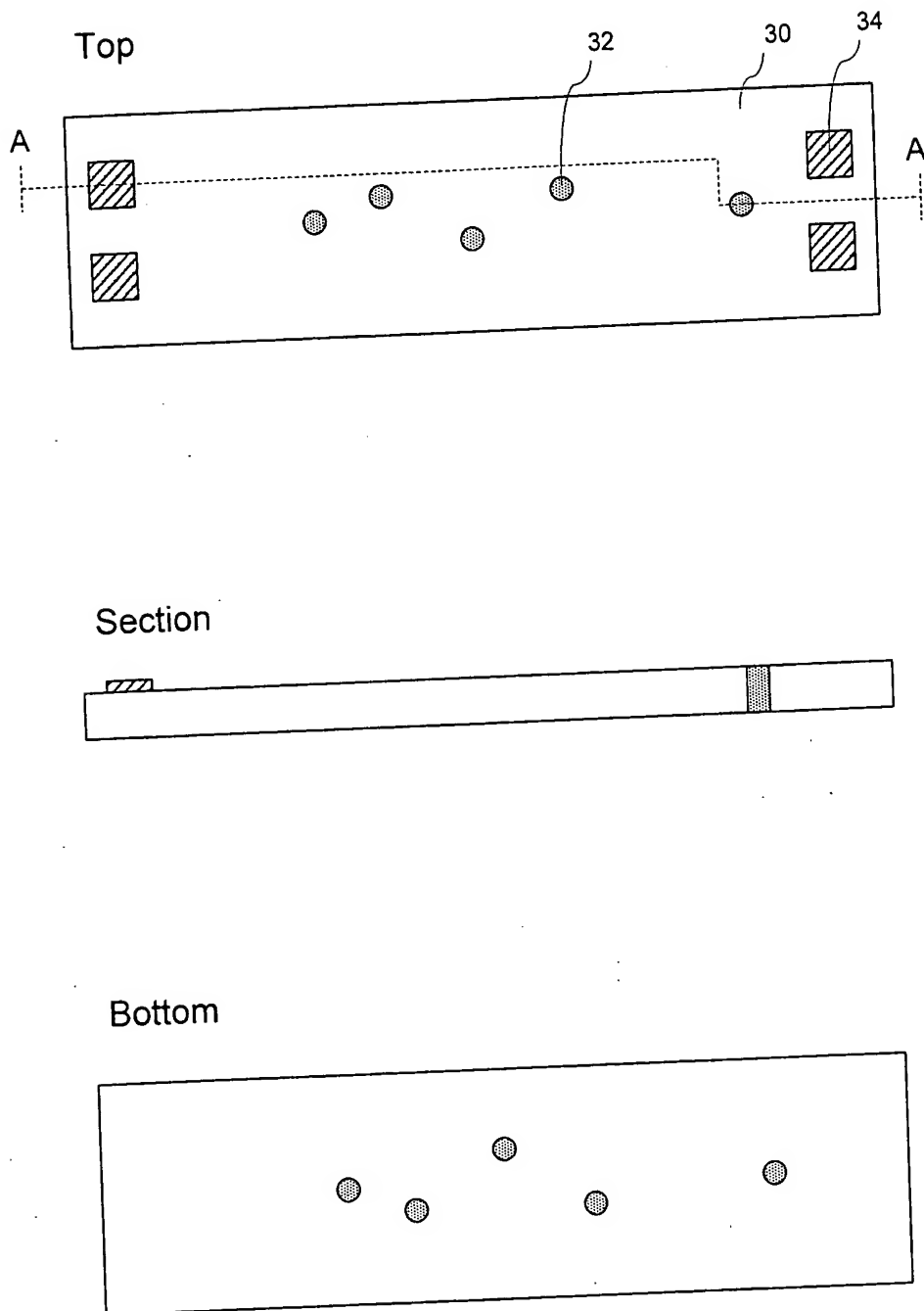


Figure 2b

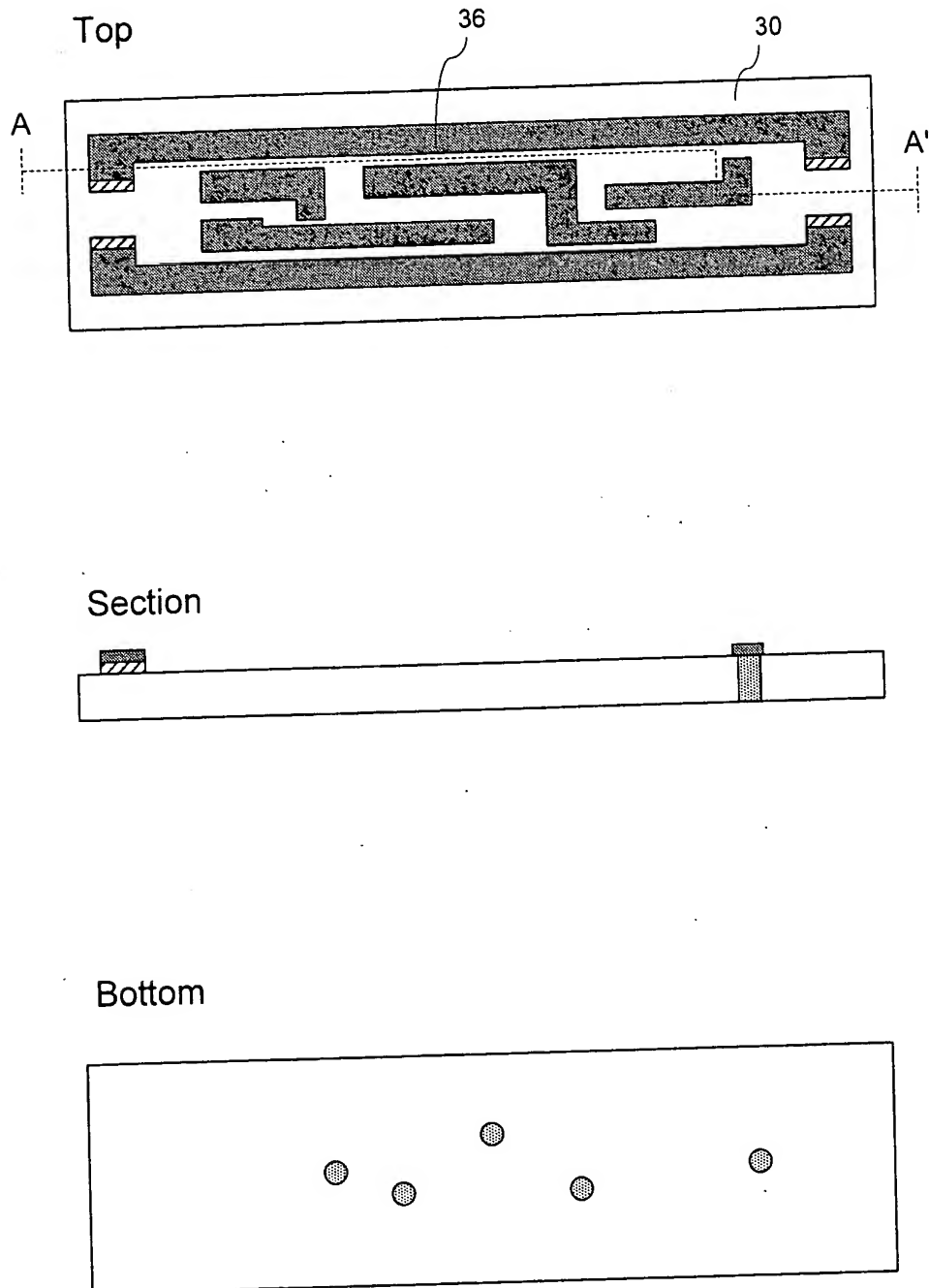


Figure 2c

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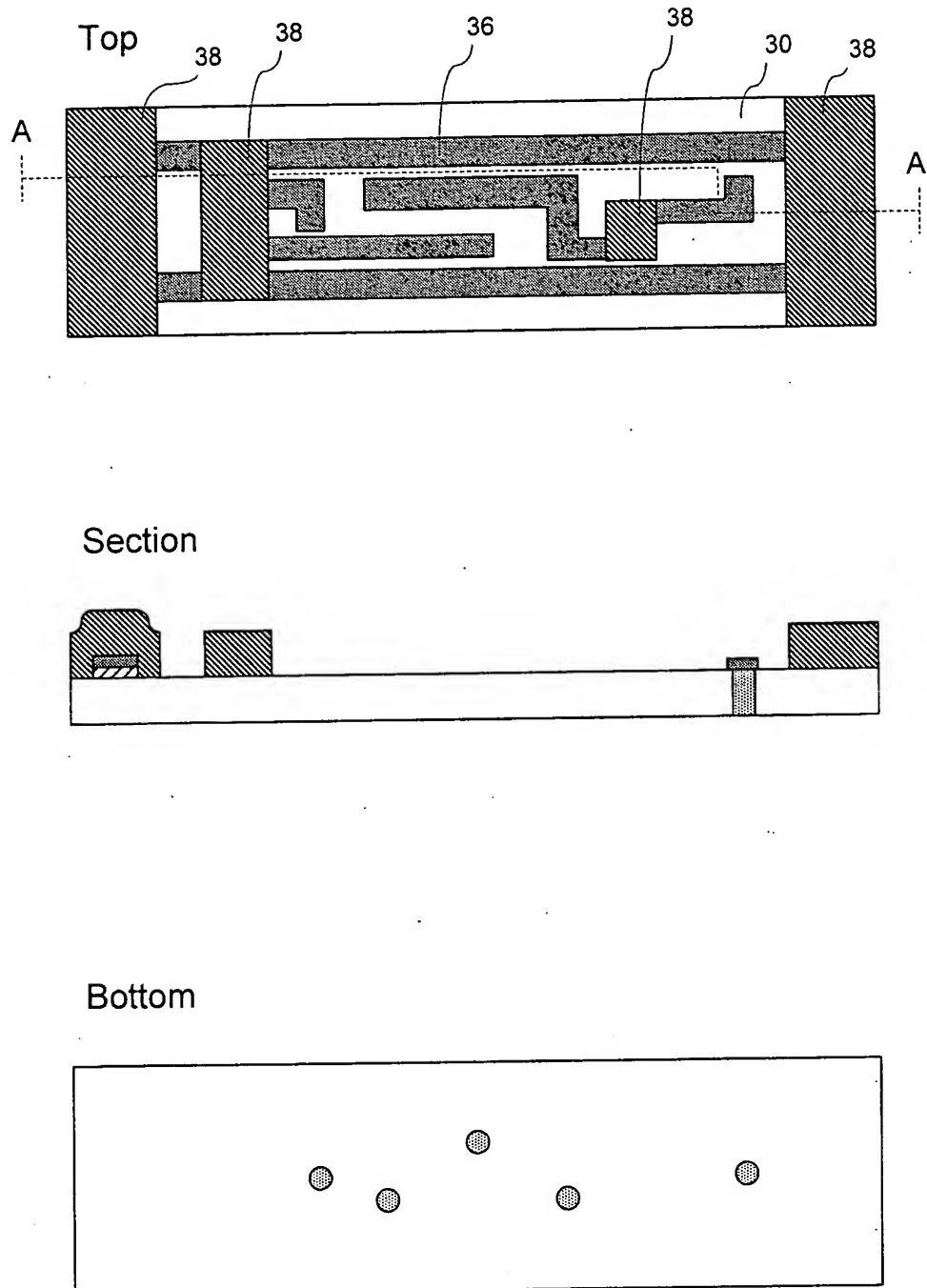


Figure 2d

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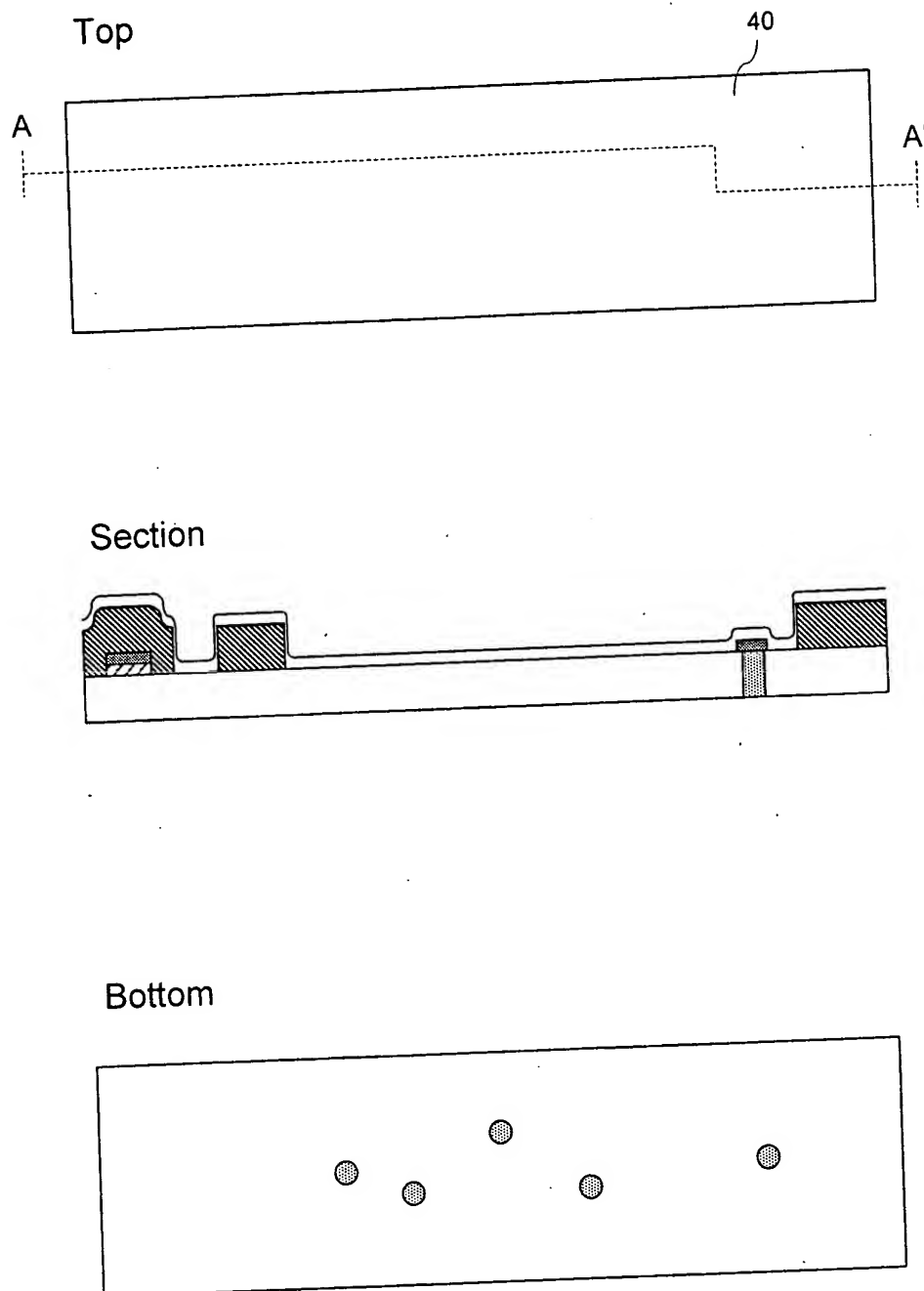


Figure 2e

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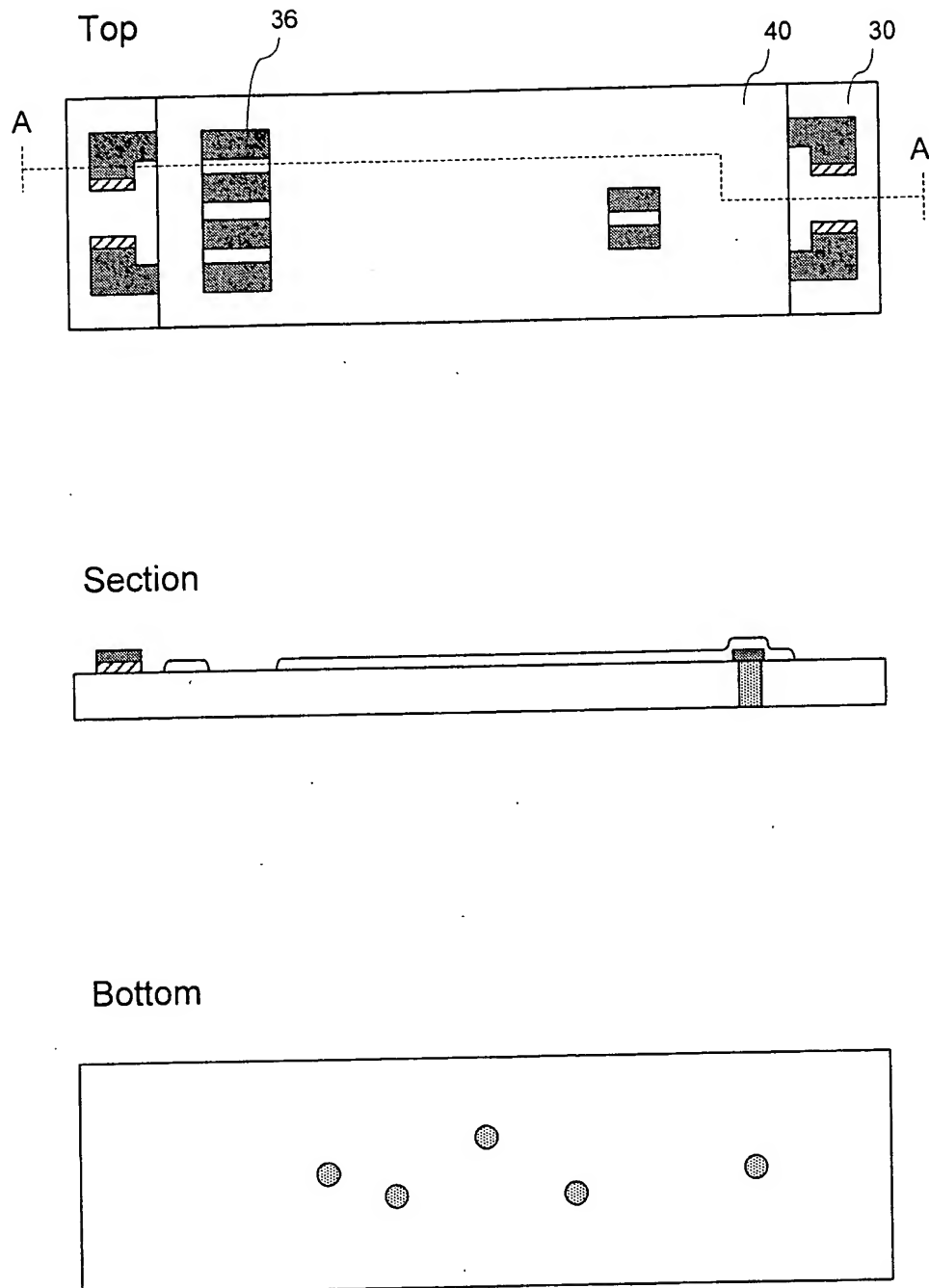


Figure 2f

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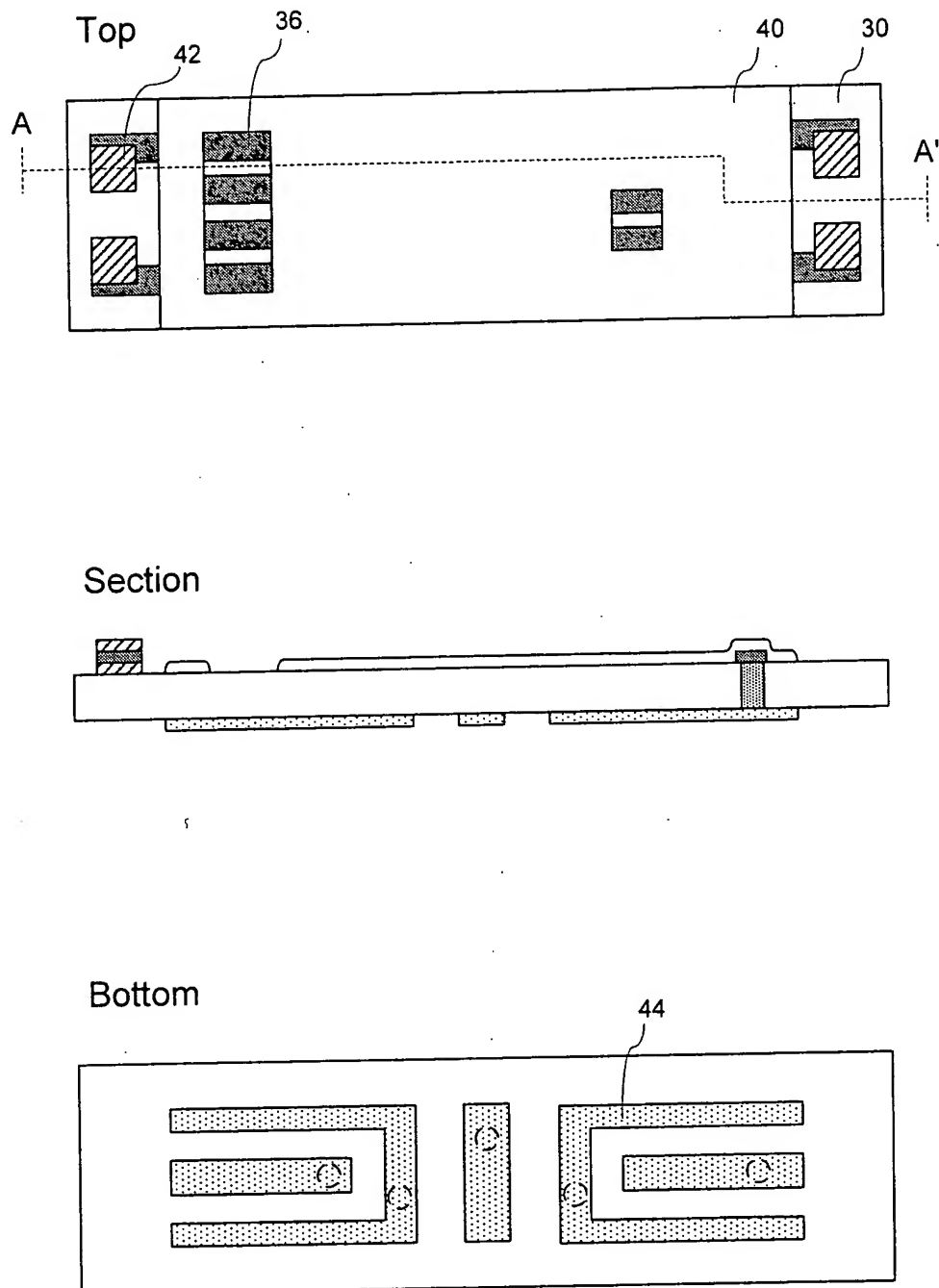
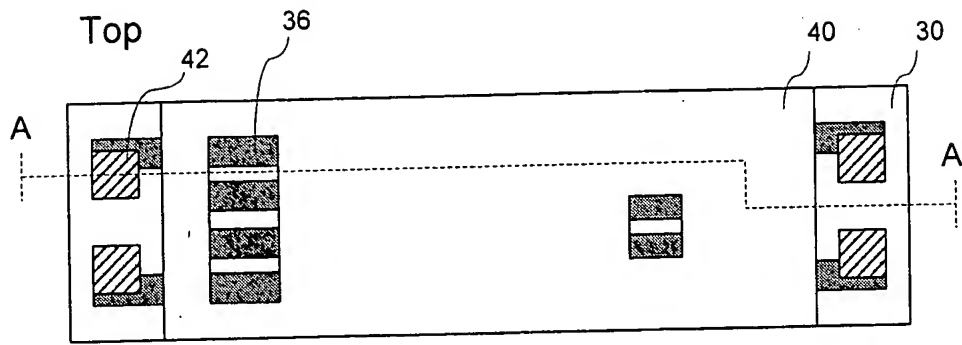


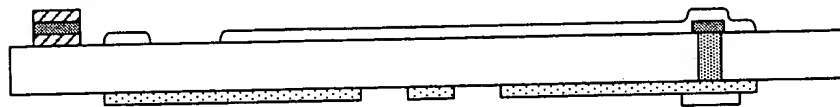
Figure 2g

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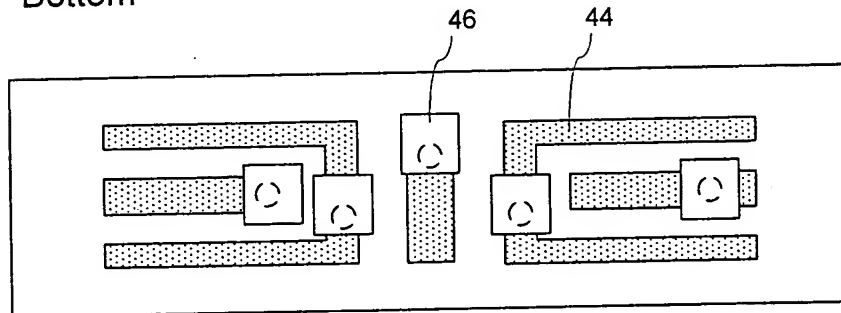


Figure 2h

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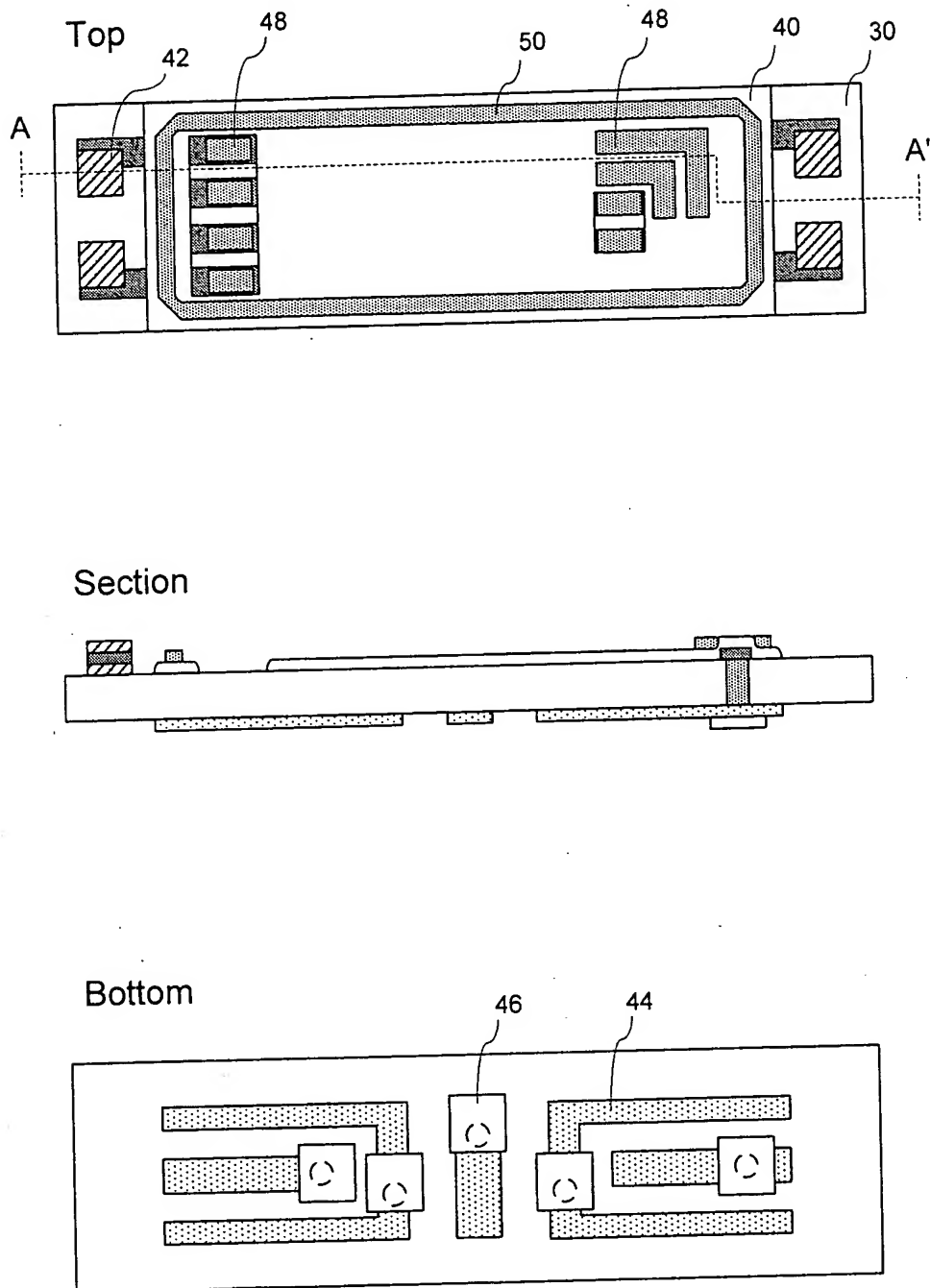


Figure 2i

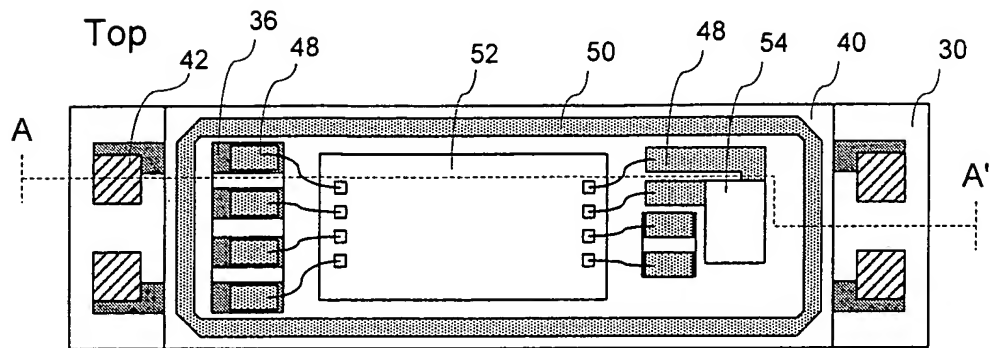
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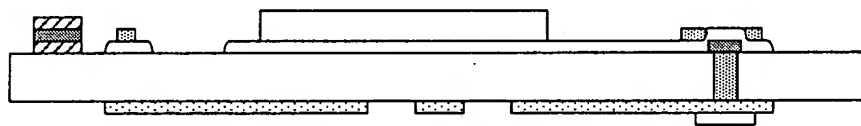
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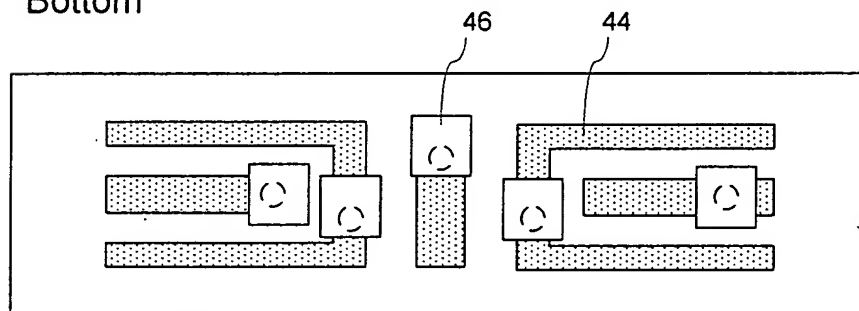


Figure 2j

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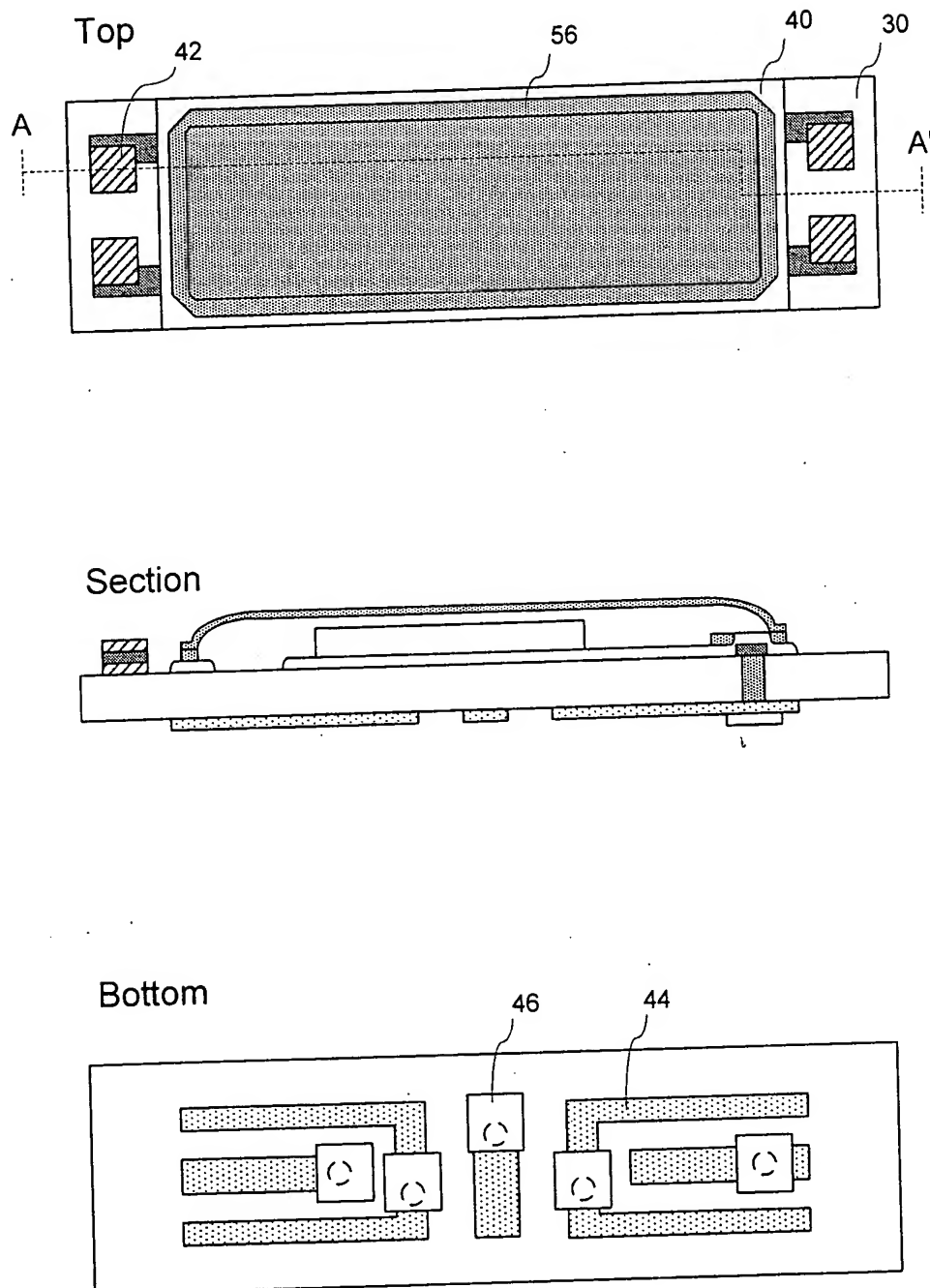


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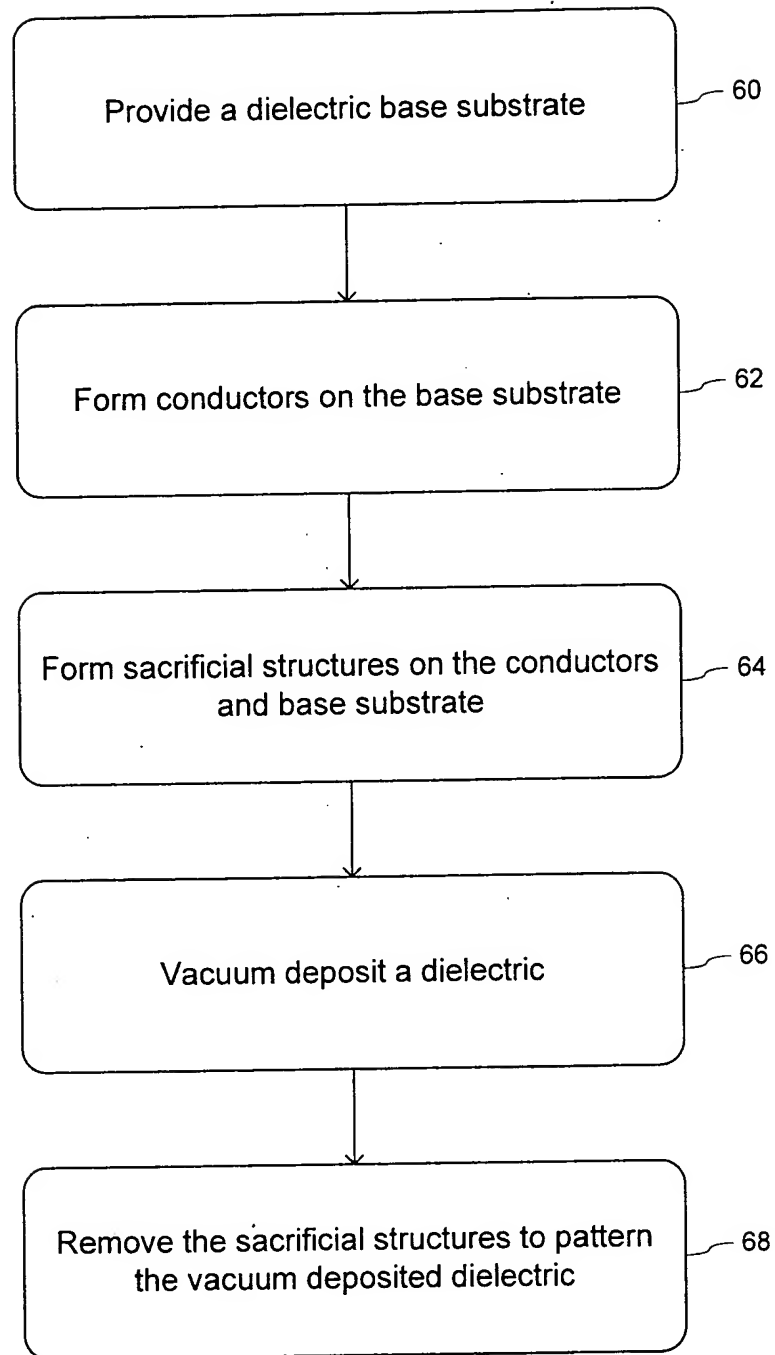


Figure 3